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TinyLogic ULP-A 2-Input Non-Inverting Multiplexer

NC7SP157

The NC7SP157 is a 2-input non-inverting multiplexer in tiny footprint packages. The device is designed to operate for $V_{CC} = 0.9 \text{ V}$ to 3.6 V.

Features

- Designed for 0.9 V to 3.6 V V_{CC} Operation
- 2.9 ns t_{PD} at 3.3 V (Typ)
- Inputs/Outputs Over-Voltage Tolerant up to 3.6 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 2.6 mA at 3.3 V
- Available in SC-88 and MicroPakTM Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

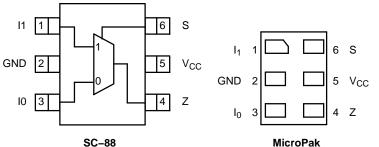


Figure 1. Pinout Diagrams (Top Views)

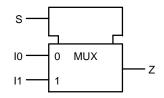


Figure 2. Logic Symbol

PIN ASSIGNMENT

Pin	SC88	MicroPak
1	11	11
2	GND	GND
3	10	10
4	Z	Z
5	V _{CC}	V _{CC}
6	S	S

FUNCTION TABLE

	Inputs	Output	
S	11	10	Z = I0 x S + I1 x S
L	Х	L	L
L	Х	Н	н
Н	L	Х	L
Н	Н	Х	Н





= Assembly Plant Code



XXX = Specific Device Code

= Date Code M

= Pb-Free Package

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 6 of this data sheet.

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MAXIMUM RATINGS

Symbol	Characteris	tics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +4.3	V
V _{IN}	DC Input Voltage		-0.5 to +4.3	V
V _{OUT}	DC Output Voltage	Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +4.3 -0.5 to +4.3	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
I _{OUT}	DC Output Source/Sink Current		±50	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground	d Pin	±50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 S	Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC–88 MicroPak	377 154	°C/W
PD	Power Dissipation in Still Air	SC–88 MicroPak	332 812	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

 Applicable to devices with outputs that may be tri-stated.
 Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Para	Min	Max	Unit	
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V _{IN}	DC Input Voltage	0	3.6	V	
V _{OUT}	DC Output Voltage	Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 3.6 3.6	
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Transition Rise and Fall Time	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

				T _A = 25°C			T _A = -40°C to +85°C		
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
VIH	High-Level Input		0.9	-	0.5	_	-	_	V
Voltage	Voltage		1.1 to 1.3	$0.65 \times V_{CC}$	-	_	0.65 x V _{CC}	_	
		1.4 to 1.6	$0.65 \times V_{CC}$	-	_	0.65 x V _{CC}	-		
			1.65 to 1.95	$0.65 \times V_{CC}$	-	-	$0.65 \times V_{CC}$	-	
			2.3 to 2.7	1.6	-	-	1.6	-	
			3.0 to 3.6	2.1	-	-	2.1	-	
V_{IL}	Low-Level Input		0.9	-	0.5	_	_	_	V
	Voltage		1.1 to 1.3	-	-	0.35 x V _{CC}	-	0.35 x V _{CC}	1
			1.4 to 1.6	-	-	0.35 x V _{CC}	-	0.35 x V _{CC}	
			1.65 to 1.95	-	-	0.35 x V _{CC}	-	0.35 x V _{CC}	1
			2.3 to 2.7	-	_	0.7	-	0.7	
			3.0 to 3.6	-	_	0.9	-	0.9	1
V _{OH}	High-Level Output	$V_{IN} = V_{IH} \text{ or } V_{IL}$							V
	Voltage	I _{OH} = -20 μA	0.9	-	V _{CC} - 0.1	-	-	-	
			1.1 to 1.3	V _{CC} – 0.1	-	-	V _{CC} – 0.1	_	
			1.4 to 1.6	V _{CC} – 0.1	-	_	V _{CC} – 0.1	_	
			1.65 to 1.95	V _{CC} – 0.1	-	_	V _{CC} – 0.1	_	1
			2.3 to 2.7	V _{CC} – 0.1	-	-	V _{CC} – 0.1	-	1
			3.0 to 3.6	V _{CC} – 0.1	-	-	V _{CC} – 0.1	-	1
		I _{OH} = -0.5 mA	1.1 to 1.3	0.75 x V _{CC}	-	_	0.70 x V _{CC}	_	
		I _{OH} = -1 mA	1.4 to 1.6	1.07	-	_	0.99	_	
		I _{OH} = -1.5 mA	1.65 to 1.95	1.24	-	_	1.22	_	1
		I _{OH} = -2.1 mA	2.3 to 2.7	1.95	-	_	1.87	_	
		I _{OH} = -2.6 mA	3.0 to 3.6	2.61	-	_	2.55	_	
V _{OL}	Low-Level Output	$V_{IN} = V_{IH} \text{ or } V_{IL}$							V
	Voltage	I _{OL} = 20 μA	0.9	-	0.1	_	_	_	1
			1.1 to 1.3	-	-	0.1	-	0.1	1
			1.4 to 1.6	-	-	0.1	_	0.1	1
			1.65 to 1.95	-	-	0.1	_	0.1	
			2.3 to 2.7	-	-	0.1	-	0.1	1
			3.0 to 3.6	-	-	0.1	-	0.1	
		I _{OL} = 0.5 mA	1.1 to 1.3	-	-	0.3 x V _{CC}	-	0.3 x V _{CC}	
		I _{OL} = 1 mA	1.4 to 1.6	-	-	0.31	-	0.37	
		I _{OL} = 1.5 mA	1.65 to 1.95	-	-	0.31	-	0.35]
		I _{OL} = 2.1 mA	2.3 to 2.7	-	-	0.31	-	0.33]
		I _{OL} = 2.6 mA	3.0 to 3.6	-	-	0.31	-	0.33	1
I _{IN}	Input Leakage Current	$V_{IN} = 0 V \text{ to } 3.6 V$	0.9 to 3.6	_	-	±0.1	_	±0.5	μA
I _{OFF}	Power Off Leakage Current	$V_{IN} = 0 V$ to 3.6 V or $V_{OUT} = 0 V$ to 3.6 V	0	_	-	0.5	_	0.5	μA
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	0.9 to 3.6	-	-	0.9	-	0.9	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

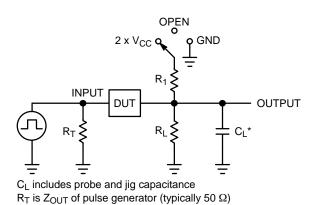
AC ELECTRICAL CHARACTERISTICS

				٦	T _A = 25°0	C	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay,	$R_L = 1 M\Omega$, $C_L = 10 pF$	0.9	-	54.5	-	-	-	ns
	(S or I0 or I1) to Z (Figures 3 and 4)		1.10 to 1.30	-	14.6	32.3	-	37.7	
	,		1.40 to 1.60	-	7.6	15.1	_	16.8	
			1.65 to 1.95	-	5.4	11.5	_	12.5	
			2.3 to 2.7	-	3.6	8.1	_	9.1	
			3.0 to 3.6	-	2.9	6.6	_	7.7	
t _{PLH} , t _{PHL}	Propagation Delay,	S or I0 or I1) to Z	0.9	-	55.9	-	-	-	ns
	(S or 10 or 11) to Z (Figures 3 and 4)		1.10 to 1.30	-	15.1	33.7	-	39.7	
			1.40 to 1.60	-	8.0	16.0	-	17.2	
			1.65 to 1.95	-	5.8	12.1	-	13.1	
			2.3 to 2.7	-	3.8	8.6	-	9.7	
			3.0 to 3.6	-	3.1	7.0	-	8.1	
t _{PLH} , t _{PHL}	Propagation Delay,	$R_L = 1 M\Omega$, $C_L = 30 pF$	0.9	-	60.2	-	-	-	ns
	(S or I0 or I1) to Z (Figures 3 and 4)		1.10 to 1.30	-	16.7	37.8	-	47.7	
			1.40 to 1.60	-	9.3	18.6	-	19.5	
			1.65 to 1.95	-	6.9	14.1	-	15.3]
			2.3 to 2.7	-	4.5	10.0	-	11.2	
			3.0 to 3.6	-	3.7	8.2	_	9.3	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition	Typical (T _A = 25°C)	Unit
C _{IN}	Input Capacitance	$V_{CC} = 0 V$	2.0	pF
C _{OUT}	Output Capacitance	$V_{CC} = 0 V$	4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	f = 10 MHz, V_{CC} = 0.9 to 3.6 V, V_{IN} = 0 V or V_{CC}	8.0	pF

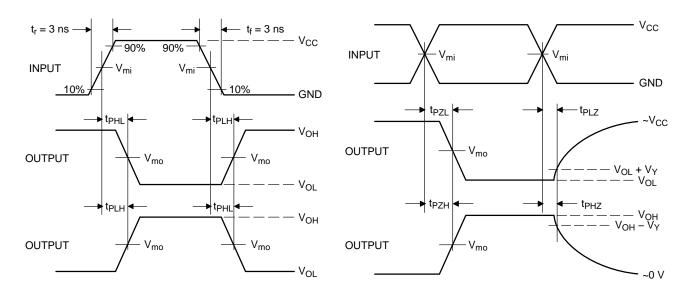
5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption: $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



f = 1 MHz

Test	Switch Position
t _{PLH} / t _{PHL}	Open
t _{PLZ} / t _{PZL}	2 x V _{CC}
t _{PHZ} / t _{PZH}	GND

Figure 3. Test Circuit



V _{CC} , V	V _{mi} , V	V _{mo} , V	V _Y , V
0.9	V _{CC} / 2	V _{CC} / 2	0.1
1.1 to 1.3	V _{CC} / 2	V _{CC} / 2	0.1
1.4 to 1.6	V _{CC} / 2	V _{CC} / 2	0.1
1.65 to 1.95	V _{CC} / 2	V _{CC} / 2	0.15
2.3 to 2.7	V _{CC} / 2	V _{CC} / 2	0.15
3.0 to 3.6	1.5	1.5	0.3

Figure 4. Switching Waveforms

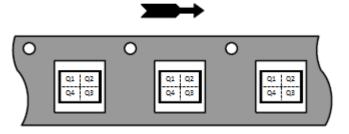
ORDERING INFORMATION

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping [†]
NC7SP157P6X	SC-88	PF7	Q4	3000 / Tape & Reel
NC7SP157L6X	MicroPak	L7	Q4	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pin 1 Orientation in Tape and Reel

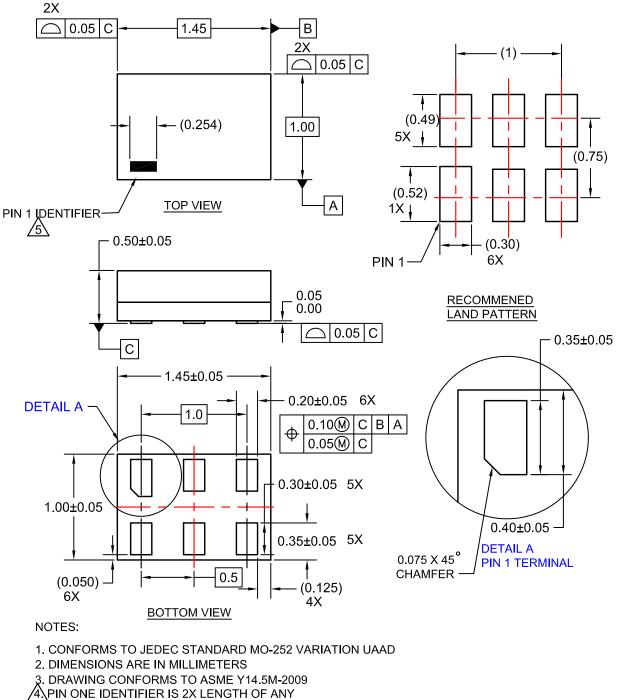
Direction of Feed



MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

PACKAGE DIMENSIONS

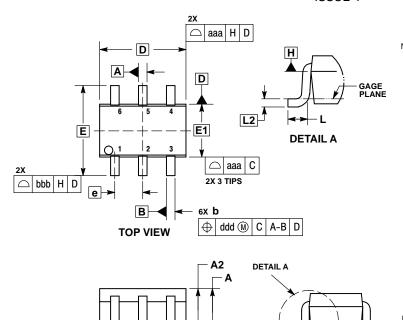
SIP6 1.45X1.0 CASE 127EB ISSUE O



OTHER LINE IN THE MARK CODE LAYOUT.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**



NOTES:

С

END VIEW

- NOTES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
 DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
 DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION
- LEAD BE IWEEN 0.08 AND 0.15 FROM THE TIP. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION & AT MAXIMUM MATERIAL CONDI-TION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. 7.

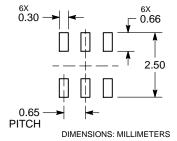
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α			1.10			0.043	
A1	0.00		0.10	0.000		0.004	
A2	0.70	0.90	1.00	0.027	0.035	0.039	
b	0.15	0.20	0.25	0.006	0.008	0.010	
С	0.08	0.15	0.22	0.003	0.006	0.009	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	2.00	2.10	2.20	0.078	0.082	0.086	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65 BS	С	0.026 BSC			
L	0.26	0.36	0.46	0.010	0.014	0.018	
L2		0.15 BS	SC	0.006 BSC			
aaa	0.15			0.006			
bbb	0.30			0.012			
CCC	0.10			0.004			
ddd		0.10			0.004		

RECOMMENDED SOLDERING FOOTPRINT*

SIDE VIEW

A1

6X 🗀 ccc C



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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